

**FEE TRANSMITTAL**

Electronic Version v10

Stylesheet Version v10

**Title of  
Invention**

Bond Pad Structure Comprising Multiple Bond Pads with metal Overlap

Application Number : 09/927675



Date : 2001-08-10

First Named Applicant: Guy Perry

Attorney Docket Number: MTI-31471

Art Unit: 2815

Examiner : Chris C Chu

**TOTAL FEE AUTHORIZED \$ 180**

Patent fees are subject to annual revisions on or about October 1st of each year.

Fee Description	Fee Code	Amount \$	Fee Paid \$
Submission Of Information Disclosure Stmt Fee	1806	180	180

**AUTHORIZED BILLING INFORMATION****The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:**

Deposit account number: 232053

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Deposit name: Whyte Hirschboeck Dudek SC

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Date (YYYYMMDD): 2005-07-15